

DSG-RICH R&D Meeting

Date: May 17, 2021

Time: 11:00AM – 12:00PM

Attendees: Mary Ann Antonioli, Peter Bonneau, Aaron Brown, Pablo Campero, Brian Eng, George Jacobs, Tyler Lemon, Marc McMullen, and Amrit Yegneswaran

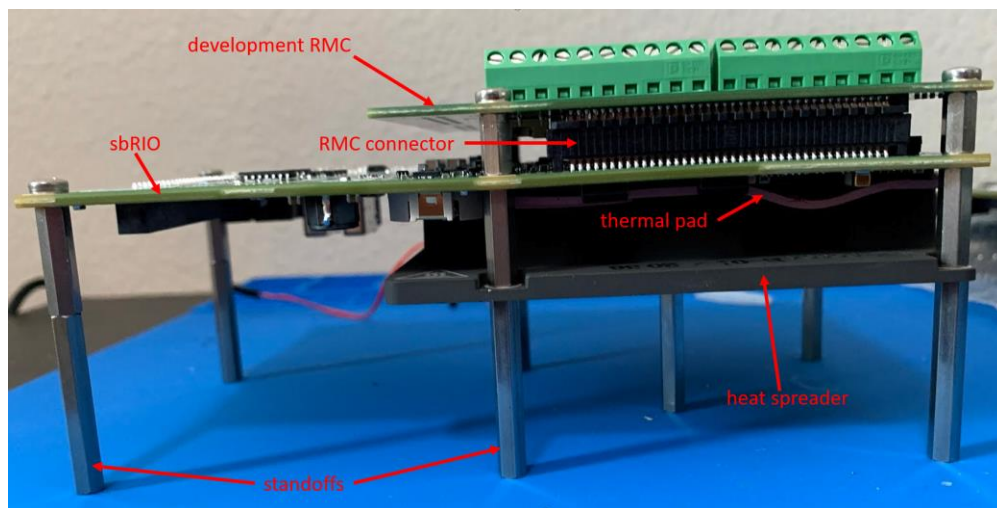
1. SHT35 sensor PCB fabrication

Peter Bonneau, Brian Eng, Tyler Lemon, and Marc McMullen

- SHT35 sensors shipped to Advanced Circuits; received on May 14, 2021

2. RICH-II interlock chassis thermal management

- sbRIO-9629 comes with kit for installing “heat spreader” onto sbRIO



Side view of sbRIO-9629 with heat spreader installed.



sbRIO held upside-down to better show heat spreader.

- RICH-II chassis will use heat spreader as a thermal conduction path
 - Thermal conduction path will use chassis as an additional heatsink for convective cooling to ambient environment
 - Chassis will be perforated (except for area directly in contact with heat spreader) to maximize ventilation for heat radiating from sides of heat spreader
 - Layout of chassis and location of components has yet to be determined

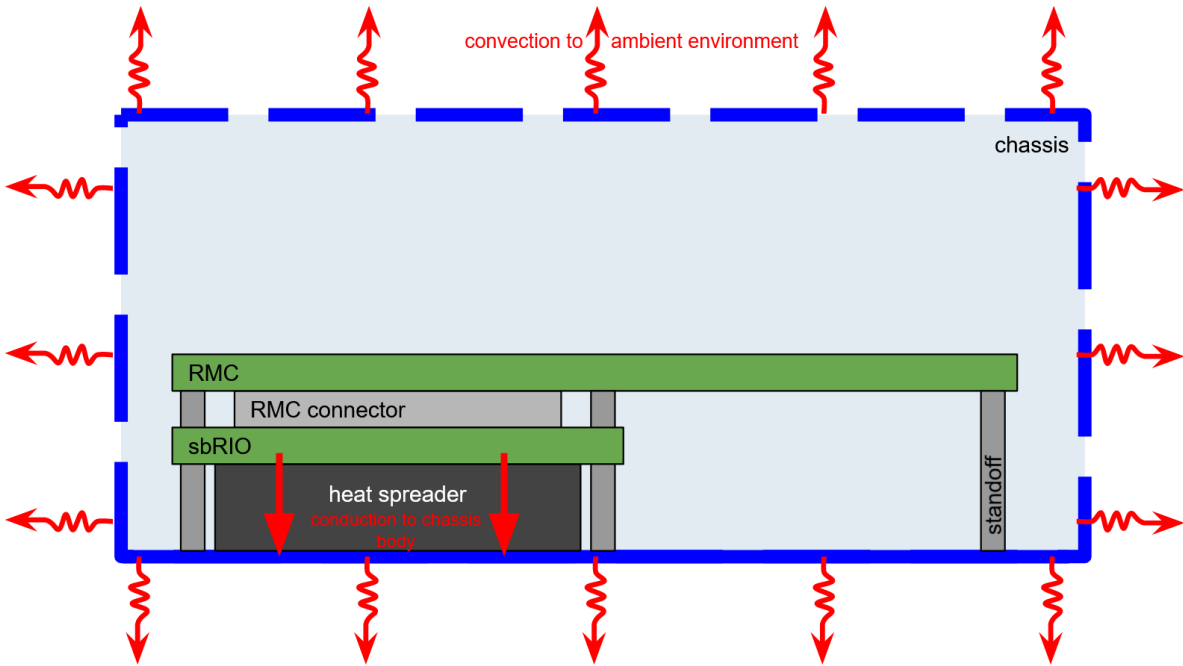


Diagram of heat spreader as thermal conduction path.
 sbRIO could also be in an inverted configuration with heat spreader in contact with top of chassis.